

Lenovo P15v i Gen 3

Version: 2.0 | 07/19/2023

SECTION I: SYSTEM OVERVIEW

Description	ThinkPad P15v i Built for creators who demand more value, the ThinkPad® P15v i closes the gap in price and performance between entry-level and high-end workstations and offers the power you need to handle large workloads and multitask with ease.
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CPU

Processor Support	Intel 12th Gen Alder Lake H Series (45W) Core i5, i7, i9
Socket Type	BGA

Operating Systems

Preloaded	Windows 11 Pro 64-bit (21H2) Windows 11 Home 64-bit (21H2) Windows 10 Pro 64-bit preinstalled through downgrade rights in Windows 11 Pro 64-bit (21H2) Windows 10 China Government Edition Ubuntu Linux 64-bit (Version 20.04 LTS, running the 4.15.0 kernel) No Operating System
Supported	Ubuntu Linux 22.04 Cert only Red Hat Enterprise Linux (RHEL) 8.6

Memory

Number of DIMM Slots	Up to 2 DIMM sockets
Channels	Single Channel w/ 1DIMM Dual Channel w/ 2DIMMs
Type	DDR5 SoDIMM
ECC Support	No

Speed	Up to 4800MHz
Max DIMM Size	32GB
Max System Memory	64GB
Min System Memory	8GB
Soldered Memory	None
Disclaimers	No ECC memory on P15v i Gen 3

Storage

Storage Slots	2 x M.2 2280
SATA	No
PCIe	Solid State Drive, OPAL2 PCIe-NVMe M.2 2280S3 - TLC
SAS	No
Interface	PCIe
Security	OPAL
Optional Hard Disk Drive Controllers	No

Video

Integrated Graphics	Processor Graphics Intel® Iris Xe Graphics Utilized via "Hybrid Mode" in BIOS
Discrete Graphics	NVIDIA T600 or T1200 or RTX A2000
Adapter	None
Bus Interface	PEG

Display

Resolutions	FHD / UHD
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Camera

Resolution	HD 720p / IR Camera
Frames per Second	30 fps
Focus	Fixed 50cm
Camera Interface	USB 2.0
IR Camera	Yes

Keyboard

Number of Keys	US : 105 / UK : 106 / JP : 110
Numpad	Yes
Size	100% ISO
Function Key Features	Yes
Backlit	Optional
Keyboard size	CS20 KYB with numberpad
Key stroke	1.5mm
Key pitch	19.05mm
Keyboard backlight	Optional
Keyboard thickness	Standard

Touchpad / Fingerprint Reader

TrackPoint Details	COMO TrackPoint module (t5.55mm)
Finger Print Reader Model	8x8 FPR, MoC w/o LED Prometheus 8x8
Multi-Touch	Yes
Resolution	1000 ppi
TouchPad/Trackpad thickness	3.3mm
TouchPad/Trackpad type	2 BCP
Trackpad size	100mm x 69mm
Trackpad material/finish	Mylar surface

I/O - Ports and Connectors

USB	2x USB-A 3.2 Gen1 (1x Powered)
Thunderbolt	1x Thunderbolt 4 (USB 4/USB-C 3.2 Gen 2/DP1.4/PD)
HDMI	1x HDMI (2.0)
Audio Combo Jack	1x Microphone & Headphone Combo Jack (3.5mm)
Media Card Reader	Dedicated SD Card Reader (UHS-II) (MMC,SD,SDHC SDXC)
Smart Card Reader	Yes (optional)
Power Connector	DC-In
Docking Port	Docking Via Thunderbolt 4 / USB-C
VirtualLink	None
Network adapter	Gigabit Ethernet (RJ45)

Power Connector

Main	DC-In
USB-C	1x Thunderbolt 4 (USB-C/DP/PD)

Ethernet

Vendor	Intel
Count	x1
EEPROM	SPI ROM (Merge with BIOS/MEFW)
Speeds	10/100/1000 Mbps
Functions	Wake On LAN MAC Address Pass Through PXE Boot Flash Over LAN
Connectors	RJ45

WWAN

Model	Optional: Fibocom L860-GL 4G LTE CAT16 with eSIM
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Near Field Communications

Model	No NFC Support
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Audio

Vendor	Realtek
Type	Intel High Definition Audio
Internal Speaker	2 channel
Connectors	Microphone & Headphone Combo Jack (3.5mm)
Chipset	ALC3287
Number of Channels	4-channel DAC, 4-channel ADC
Number of Bits/Audio Resolution	16/20/24-bit PCM format
Sampling Rate (Recording/Playback)	44.1K/48K/96K/192KHz sample rate
Signal to Noise Ratio	Mic In: 90dB FSA Headphone Out@32ohm: 97dB FSA

Analog Audio	None
Dolby Digital	Dolby Audio SW Support
Digital Out (S/PDIF)	No
Speaker Power Rating	2W@4ohm/ch

Power adapter

Type	135W AC Adapter
Dimensions	200cc (118 x 77 x 22)
Input Voltage	100-240V

Security

TPM	Version 2.0
Asset ID	Yes
vPro	Intel vPro for WS

Chassis Information

Format	Clamshell
Color	GS Black
Thermal Solutions	Internal single FAN, Intelligent Cooling
Dimensions	Length 14.43 inches 366.5 millimeters Width 9.84 inches 250 millimeters Height 0.89 inches (Thickest 0.95 inches, Thinnest 0.83 inches) 22.7 millimeters (Thickest 24.2mm, Thinnest 21.17mm)
Weight	Starting at with UMA UHD: 6 Cell Battery 4.62lbs/2.09kg

Packaging Parameters

Height (mm)	330
Height (inch)	13
Width (mm)	521
Width (inch)	20.5
Depth (mm)	90

Depth (inch)	3.5
Weight (kgs)	Retail:3.32kgs
Weight (lbs)	Retail:7.32bs

Security & Serviceability

Hardware Maintenance Manual	P15v i Gen 3 HMM – need link
Drivers & Software	P15v i Gen 3 Drivers & Software – need link
Self Healing BIOS	Yes
Access Panel	Removeable bottom cover
Number of Screws	9
Swappable Components	Bottom cover, memory module, M.2 solid-state drive, speaker assembly, coin-cell battery, TrackPoint pointing cap
Storage Slots	2 slots
Memory	2 SoDIMM slots
System Board	FR4
Restore CD/DVD/USB Set	None, Restore Media available via Lenovo Customer Support Center
Cable Lock Support	Security-lock slot, Optional Kensington Cable Lock
Power-On Password	Yes
Hard Disk Password	Yes; User and Master hard disk password
Supervisor Password	Yes
NIC LEDs (integrated)	None
Security Chip	Yes (for TMP 2.0)
Access Panel Key Lock	Bottom Cover Tamper Detection
Boot Sequence Control	Yes

Operating Environment

Operating – Air Temperature	At altitudes up to 2438 m (8000 ft) - Operating: 5°C to 35°C (41°F to 95°F)
Non Operating – Air Temperature	At altitudes up to 2438 m (8000 ft) - Storage: 5°C to 43°C (41°F to 109°F)
Humidity	Operating: 8% to 95% at wet-bulb temperature 23°C (73°F) Storage: 5% to 95% at wet-bulb temperature 27°C (81°F)
Corrosive Gas	G1
Particulates	P1

SECTION II: SUPPORTED COMPONENTS

Supported Components

Processor	Intel® Core™ i5-12500H processor (E-cores up to 3.30 GHz P-cores up to 4.50 GHz) Intel® Core™ i7-12700H processor (E-cores up to 3.50 GHz P-cores up to 4.70 GHz) Intel® Core™ i7-12800H vPro processor (E-cores up to 3.70 GHz P-cores up to 4.80 GHz) Intel® Core™ i9-12900H vPro processor (E-cores up to 3.80 GHz P-cores up to 5.00 GHz)
Memory Support	DDR5 4800MHz SoDIMM
Chipset (PCH)	Mobile Intel® WM690 Chipset
Size of BIOS Flash	32MB
Super I/O	None
Clock	Crystal
Audio	Realtek High Definition Audio
Ethernet	Native Intel Ethernet Connection I219-V (Non-vPro) or I219-LM (vPro) via bundled or optional ThinkPad Ethernet Extension Cable

Memory

System Capacity Options	8GB 16GB 32GB 64GB
Memory Types	8GB DDR5 4800MHz SoDIMM 16GB DDR5 4800MHz SoDIMM 32GB DDR5 4800MHz SoDIMM
Brand of Memory	Samsung SK Hynix Micron Ramaxel
Memory clock frequency(MHz)	4800MHz
Disclaimers	No ECC memory on P15v i Gen 3

Storage

2.5" SAS Hard Disk Drive (HDD)	None
2.5" SATA Hard Disk Drive (HDD)	None

2.5" SATA Solid State Drive (SSD)	None
M.2 (NGFF) PCIe Solid State Drive (SSD)	256GB OPAL2 PCIe 4x4 Value TLC (M.2 2280-S3) 512GB OPAL2 PCIe 4x4 Value TLC (M.2 2280-S3) 1TB OPAL2 PCIe 4x4 Value TLC (M.2 2280-S3) 512GB OPAL2 PCIe 4x4 Performance TLC (M.2 2280-S3) 1TB OPAL2 PCIe 4x4 Performance TLC (M.2 2280-S3) 2TB OPAL2 PCIe 4x4 Performance TLC (M.2 2280-S3)
2.5" PCIe Solid State Drive (SSD)	None
Brand of Drive	Samsung Toshiba WD Micron UMIS
Intel Optane Storage Technology	None
RAID	Optional, Selectable in BIOS
RAID Level and Requirements	RAID-0/1

Removeable Media

Media Card Reader Specifications	UHS-II
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SECTION III: Supported Component Detail

CPU Specifications

CPU	Intel® Core™ i5-12500H Non vPro	Intel® Core™ i7-12700H Non vPro	Intel® Core™ i7-12800H vPro	Intel® Core™ i9-12900H vPro processor (E-cores up to 3.80 GHz P-cores up to 5.00 GHz)
Integrated Graphics	Intel® Iris Xe Graphics	Intel® Iris Xe Graphics	Intel® Iris Xe Graphics	Intel® Iris Xe Graphics
# of Cores	12	14	14	6 P-cores and 8 E-cores
# of Threads	16	20	20	20
Processor Base Frequency	2.5GHz on P-cores and 1.8GHz on E-cores	2.3GHz on P-cores and 1.7GHz on E-cores	2.4GHz on P-cores and 1.8GHz on E-cores	2.5GHz on P-cores and 1.8GHz on E-cores
Max Turbo Frequency	4.5GHz on P-cores and	4.7Ghz on P-cores and	4.8Ghz on P-cores and	5GHz on P-cores and

	3.3GHz on E-cores	3.5GHz on E-cores	3.7GHz on E-cores	3.8GHz on E-cores
Cache	18 MB	24 MB	24 MB	24 MB
TDP	45W	45W	45W	45 W

Display Specifications

Model	FHD	FHD	FHD w/oncell touch	UHD
Resolution	1920 x 1080	1920 x 1080	1920 x 1080	3840 x 2160
Diagonal	15.6"	15.6"	15.6"	15.6"
Aspect Ratio	Ratio 16:9	Ratio 16:9	Ratio 16:9	Ratio 16:9
Backlight	LED	LED	LED	LED
PPI	141 (Pixel Pitch: 0.17925mm x 0.17925mm)	141 (Pixel Pitch: 0.17925mm x 0.17925mm)	141 (Pixel Pitch: 0.17925mm x 0.17925mm)	282 (Pixel Pitch: 0.09mm x 0.09mm)
Active Area	344.16 X 193.59	344.16 x193.59	344.16 X 193.59	344.22 X 193.62
Refresh Rate	48 / 60 Hz	60Hz	48 / 60 Hz	60Hz
Contrast Ratio	800:1 (TYP)	1200:1 (TYP)	800:1 (TYP)	1400:1 (TYP)
Viewing Angle (*1)	85/85/85/85 degree		85/85/85/85 degree	85/85/85/85 degree
Color gamut	45% NTSC	100%sRGB	45% NTSC	100% Adobe
Brightness	300nit	300nit	300nit	600nit, HDR 400
Color Depth	Color depth of 45% NTSC FHD 300 nit panels is 16.2M colors (RGB 6-bits with FRC)	16M	16M	1064M
Interface	eDP 1.2	eDP 1.2	eDP 1.2	eDP 1.4
Panel ID Recognition	EDID in BIOS Table	EDID in BIOS Table	EDID in BIOS Table	EDID in BIOS Table
Weight	max 370g	Max 320g	max 360g	max 300g
Color Calibrator	None	None	None	X-Rite Factory Color Calibration
Panel Technology	IPS, Anti-Glare	IPS, Anti-Glare	IPS, Anti-Glare	IPS, Anti-Glare
Touch Panel	None	None	YES	None

SSD Specifications

M.2 (NGFF) PCIe Solid State Drive (SSD)	2x M.2 2280 PCIe
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Solid State Storage Devices

Supported Types	M.2	M.2
Dimensions inches/centimeters (W x D x H)	22.0 (+-0.15) x 80.0 (+-0.15) x 2.3 (max)	22.0 (+-0.15) x 80.0 (+-0.15) x 2.3 (max)
Size	M.2 2280 S3	M.2 2280-S3
Interface Type	PCIe NVMe	PCIe NVMe
Read/Write IOPS Specifications	Read: 250K (2TB, 1TB, 512GB), 200K (256GB) Write: 240K (2TB, 1TB, 512GB), 190K (256GB)1GB)	Read: 550K (1TB/2TB), 350K (512GB), 190K (256GB) Write: 400K (1TB/2TB), 370K (512GB), 200K (256GB) IOPS, 4K Random, 32 q depth, 8 threads
Bandwidth Performance	PCIe Gen4x4 Value (8Gb/S)	PCIe Gen4x4 Performance (16Gb/S)
Power Consumption (Max)	3.0A (duration for 10 us)	8.0W
Active(AVG)	5W	8.0W (Sequential read)
Idle	5mW (L1.2)	5mW (Low power state)
Min MTBF	2,000,000 (h)	2,000,000 (h)
Min Sequential Read	3000MB/s (2TB, 1TB, 512GB), 2900MB/s (256GB)	6400MB/s (1TB/2TB), 6000MB/s (512GB), 5000MB/s (256GB)
Min Sequential Write	1600MB/s (2TB, 1TB/512GB), 900MB/s (256GB)	5000MB/s (2TB), 3800MB/s (1TB), 3200MB/s (512GB), 1600MB/s (256GB)
Hardware Encryption	Yes	Yes for OPAL, No for Pyrite

Discrete Graphics Adapter

GPU Name	T600	T1200	RTX A2000
CUDA Processing Cores	896	1024	2560
GPU Memory	4GB	4GB	4GB
Memory Bandwidth	192GBps	192GBps	192GBps
Memory Type	GDDR6	GDDR6	GDDR6
Memory Interface	128-bit	128-bit	128-bit
Display Port	1.4	1.4	1.4
OpenGL	4.6	4.6	4.6
Shader Model	7	7	7
DirectX	12.1	12.1	12 Ultimate
PCIe Generation	4	4	4
Floating-Point Performance	3	3.7	9.3
VR Ready	No	No	No
Simultaneous Multi-Projection	N/A	N/A	74.7

NVIDIA FXAA/TXAA Antialiasing	Yes	Yes	Yes
NVIDIA nView Display Management Technology	Yes	Yes	Yes
GPU Direct for Video	Yes	Yes	Yes
Vulkan Support	Yes	Yes	Yes
NVIDIA Optimus	Yes	Yes	Yes
Disclaimers	N/A	Yes	Yes

WLAN

Model	Garfield Peak 2 Intel Wi-Fi 6E AX211 (Gig+) + BT5.2
Connector: Main, Aux/GNSS, GNSS	ANT1:AUX WiFi + BT; ANT2: Main WiFi
Antenna Diversity	Supported
MIMO	Supported
GNSS Bian	N/A
Radio ON/OFF Control	Supported
Connector interface	CNVi
Operating Temperature (Adapter Shield)	0c to +80c
Humidity Non-Operating	50%~90% Rh non condensing (at temperatures of 25c to 35c)
Operating Systems	Windows 11, 64-bit*, Microsoft Windows 10*, Linux*(limited feature support), Chrome*
Wi-Fi Alliance	Wi-Fi CERTIFIED* a/b/g/n/ac/ax with wave 2 features, WMM*, WMM-PS*, WPA*, WPA2*, WPS2*, Protected Management Frames, Wi-Fi Miracast* as Source, and Wi-Fi Direct (For Microsoft Windows* only)
IEEE WLAN Standard	IEEE 802.11a/b/g/n/ac/ax, 802.11d,802.11e, 802.11h, 802.11i, 802.11w, 802.11r, 802.11k, 802.11v, pending OS support; Fine Timing Measurement based on 802.11-2016
Roaming	Support seamless roaming between access points
Bluetooth*	Bluetooth 5.2
Authentication	WPA and WPA2, 802.1X (EAP-TLS, TTLS, PEAP, LEAP, EAP-FAST), EAP-SIM, EAP-AKA, EAP-AKA
Authentication Protocols	PAP, CHAP, TLS, MS-CHAP*, MS-CHAPv2
Encryption	64-bit and 128-bit WEP, 128-bit AES-CCMP
Regulatory	For a list of country approvals, please contact your local Intel representatives.
US Government	FIPS, FISMA
Product Safety	UL,C-UL,CB (IEC 60950-1)
Disclaimers	6GHz channel of Wi-Fi 6E is only available with Windows 11

Battery

Dimension	L: 86mm*W: 242mm*T 9.1mm
Weight	Max 290g
Type (Chemistry and Cell)	Li-Polymer (3S2P), 6-cell
Voltage	11.55 V
Battery Capacity	68Whr
Charging Time	0% to 100% 0% to 80% Battery [Wh] 68 54 Battery Charging Time (in-operation) 2hrs 1 hr Battery Charging Time (off) 1.86hrs 0.96 hr
Operating Temperature Range	between 10°C (50°F) and 35°C (95°F)
Warranty	1 Year / 3 Year Available
Coin Cell Battery (Model)	CR2032

SECTION IV: BIOS / Certifications / Standards / Environmental

BIOS Specifications

WMI Support	Yes, if it is BIOS Setup change by WMI.
ROM-Based Setup Utility (F1)	Yes
Replicated Setup	Yes, it supported with SRSETUP tool.
Boot Control	Yes, it means Boot order change.
Discrete Mode	Yes
Asset Tag	Yes
Remote Wakeup/Remote Shutdown	Yes, if Remote wakeup is Wake on LAN from S4/S5.
Per-port Control	Yes, if it is I/O port enable/disable by BIOS Setup.
Adaptive Cooling	Yes, if it is thermal & fan control.
Security	Yes, BIOS password / Hard disk password / Finger print
Intel(R) AMT (includes ASF 2.0)	Yes. If you select vPro model
Intel(R) TXT	Yes. If you select vPro model

EMC & Safety

EMC	<p>Published, Certified Existing Reports</p> <p>EMC - Australia EMC - Belarus EMC - Canada EMC - China EMC - EU/EFTA EMC - Japan EMC - Kazakhstan EMC - New Zealand EMC - Russia EMC - South Korea EMC - Taiwan EMC - USA/Territories Not Applicable / Not Required EMC - Israel EMC - Moldova EMC - Serbia EMC - Turkey EMC - Uzbekistan EMC - Vietnam</p>
Safety	<p>To access the latest User Guide and Safety and Warranty Guide, go to: https://support.lenovo.com Low Halogen Declaration of Conformance TNOT-2017-0040 Section 9 - Low Halogen Scorecard Homologation PCR B Compliant In the following countries: Albania, Algeria, Andorra, Angola, Antigua and Barbuda, Argentina, Armenia, Aruba, Australia, Azerbaijan, Bahamas, Bahrain, Bangladesh, Barbados, Belarus, Belize, Benin, Bermuda, Bolivia, Botswana, Burkina Faso, Burundi, Cambodia, Cameroon, Canada, Cape Verde, Cayman Islands, Central African Republic, Chad, China, Colombia, Comoros, Congo, Costa Rica, Djibouti, Dominican Republic, Egypt, El Salvador, Eritrea, Ethiopia, EU/EFTA, Fiji, Gabon, Gambia, Georgia, Ghana, Grenada, Guatemala, Guinea, Haiti, Honduras, Hong Kong, India, Indonesia, Israel, Jamaica, Japan, Jordan, Kazakhstan, Kenya, Kuwait, Laos, Lebanon, Liberia, Macau, Madagascar, Malawi, Malaysia, Mali, Mauritania, Mauritius, Mexico, Moldova, Mongolia, Morocco, Mozambique, Namibia, Nepal, New Zealand, Nicaragua, Niger, Nigeria, Oman, Pakistan, Panama, Papua New Guinea, Paraguay, Peru, Philippines, Qatar, Russia, Saudi Arabia, Senegal, Serbia, Seychelles, Sierra Leone, Singapore, South Africa, South Korea, Sri Lanka, Swaziland, Taiwan, Tajikistan, Tanzania, Thailand, Togo, Tunisia, Turkey, Turkmenistan, Uganda, Ukraine, United Arab Emirates, Uruguay, USA/Territories, Uzbekistan, Venezuela, Vietnam, Zambia, Zimbabwe, Brazil - Inmetro 170 Govt Bids, Guinea-Bissau, Lesotho</p>

Environmentals

Energy Star	<p>ENERGY STAR® Version 8.0 For more information about ENERGY STAR, go to: https://www.energystar.gov</p>
EPEAT	<p>EPEAT Gold Certification Available on select models</p>
IT ECO declaration	<p>The latest environmental information about Lenovo products is available at: https://www.lenovo.com/ecodeclaration</p>
Hazardous Substances	<p>The latest environmental information about Lenovo products is available at: https://www.lenovo.com/ecodeclaration European Union RoHS This Lenovo product, with included parts (cables, cords, and so on) meets the requirements of Directive 2011/65/EU on the restriction of the use of certain hazardous substances in electrical and electronic</p>

equipment (“RoHS recast” or “RoHS 2”).
For more information about Lenovo worldwide compliance on RoHS, go to:
<https://www.lenovo.com/rohs-communication>

Manageability

Industry Standard Specifications	This product meets the following industry standard specifications for manageability functionality:
Remote Manageability Software Solutions	Lenovo ThinkManagement Console Microsoft System Center Configuration Manager LANDesk Management Suite for Lenovo Vantage Technologies (www.landesk.com/lenovo)
System Software Manager	Lenovo ThinkStation supports software management tools from the ThinkVantage System Update suite: System Update Update Retriever
Service, Support, and Warranty	On-site Warranty and Service: Three-years, limited warranty and service offering delivers on-site, next business-day service for parts and labor and includes free telephone support 8am – 5pm. Global coverage ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering.